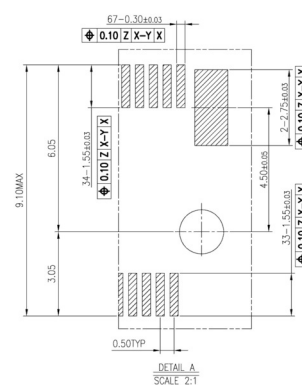
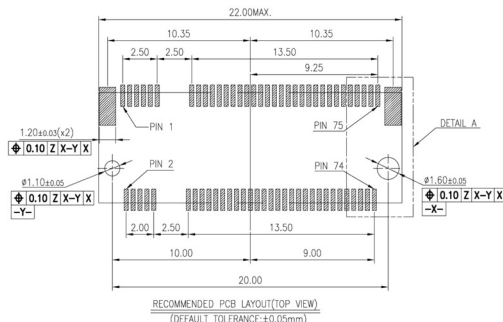
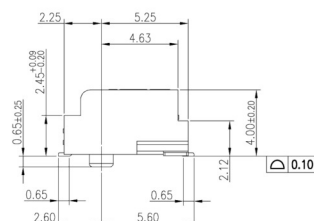
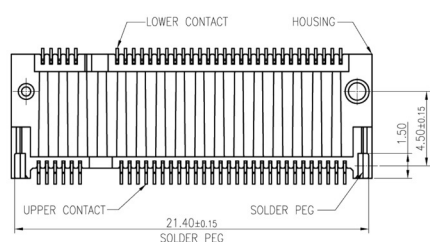
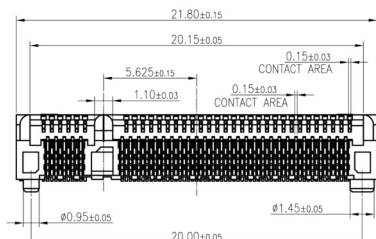
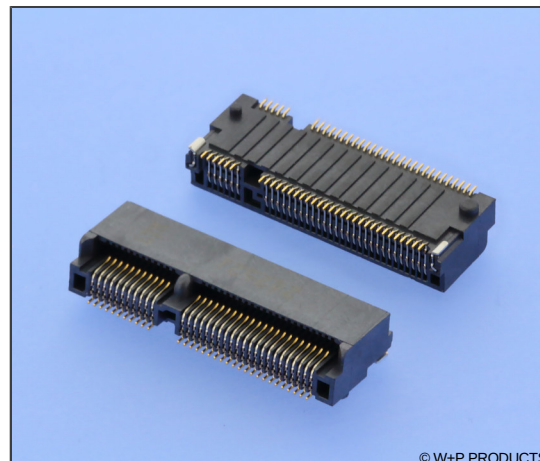
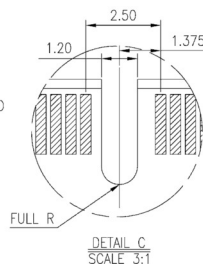
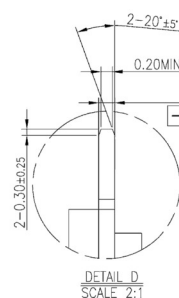
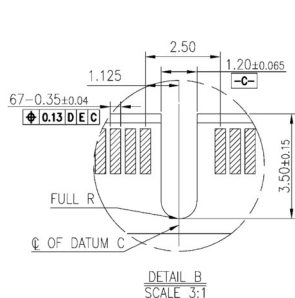
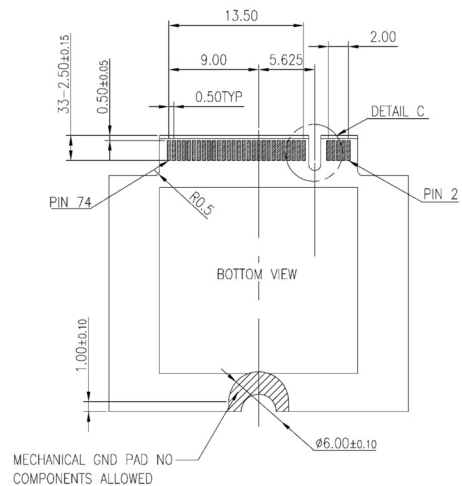
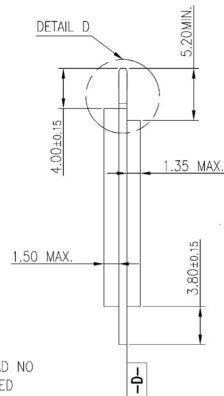
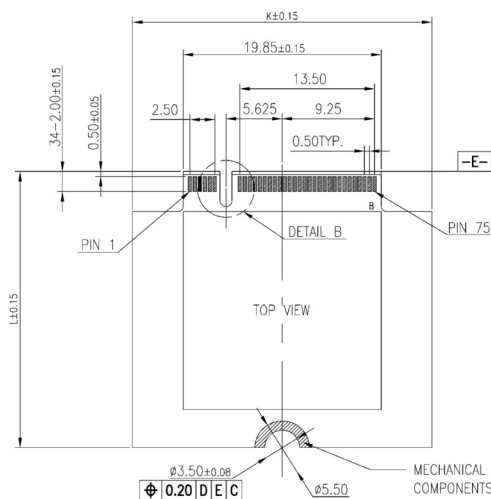
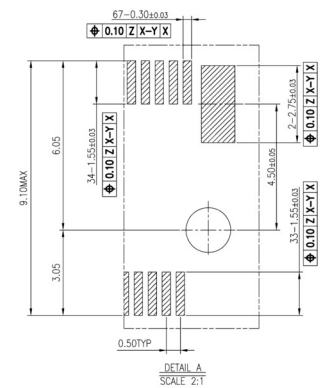


Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Im Kontaktbereich vergoldet / Lötseite verzinnt (über Ni) (andere Veredelungen auf Anfrage)
Contact Surface	Au plated contact area / Sn plated solder area (over Ni) (More plating options on request)
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 500 MΩ
Insulation Resistance	> 500 MΩ
Spannungsfestigkeit	300 V AC
Test Voltage	300 V AC
Nennspannung	50 V AC
Voltage Rating	50 V AC
Nennstrom	0,5 A
Current Rating	0.5 A
Temperaturbereich	-40 °C ... +80 °C
Temperature Range	-40 °C ... +80 °C
Verarbeitung	Reflow 260 °C für 5 sec. max.
Processing	Reflow 260 °C for 5 sec. max.



SMT M.2 (NGFF) Steckkartensockel RM 0,50mm - liegend
SMT M.2 (NGFF) Card Connector 0.50mm Pitch - horizontal

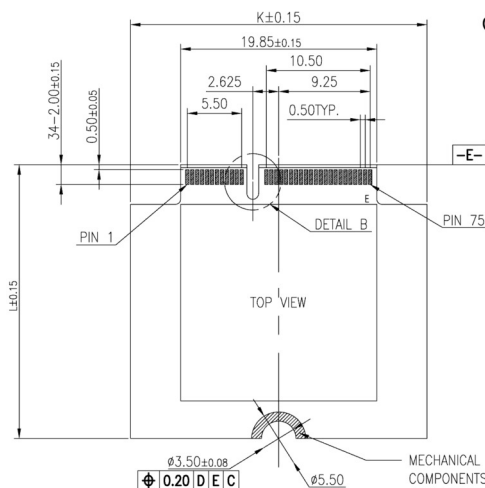


30.00	110.00	108.25
	80.00	78.25
	60.00	58.25
22.00	42.00	40.25
	30.00	28.25
	DIM. K	DIM. L

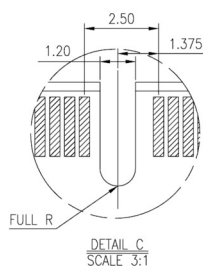
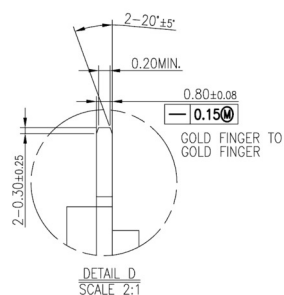
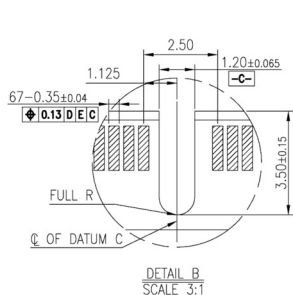
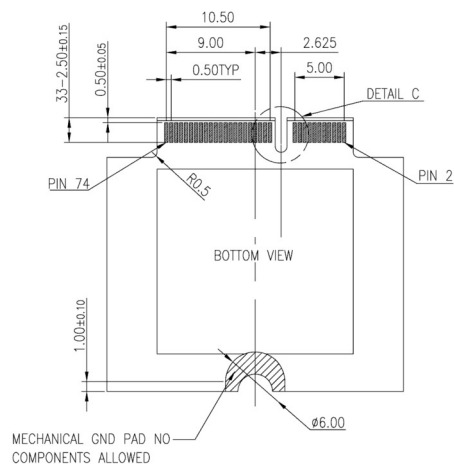
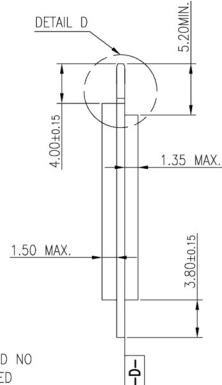
SMT M.2 (NGFF) Steckkartensockel RM 0,50mm - liegend

SMT M.2 (NGFF) Card Connector 0.50mm Pitch - horizontal

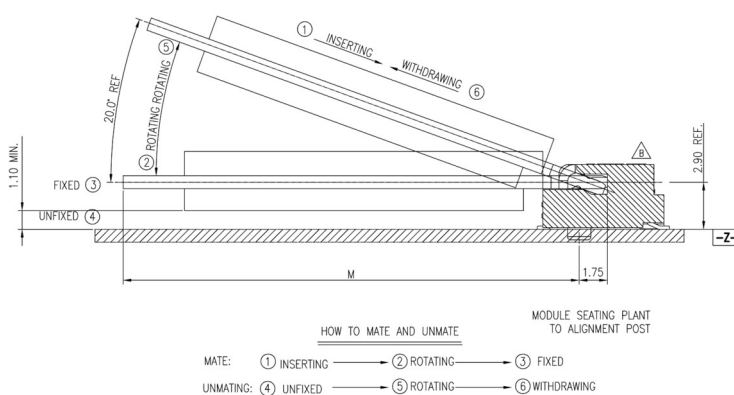
Card Dimensions and Assembly Instruction



E-Type



30.00	110.00	108.25
	80.00	78.25
	60.00	58.25
22.00	42.00	40.25
	30.00	28.25
DIM. K	DIM. L	DIM. M



Series	Contacts	Profile	Type*	Plating	Packaging
846	67	40	2	00	TR
	67	40 Bauhöhe 4,00mm Height 4.00mm	2 B (ohne P12-19) B (w/o P12-19) 3 E (ohne P24-31) E (w/o P24-31)	00 Au flash	TR

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Lieferformen / Packaging Options:

TR Tape & Reel ohne Pick&Place-Pads / Tape & Reel w/o Pick&Place-Pads

Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

